BS IEC 63011-3:2018

BSI Standards Publication

Integrated circuits – Three dimensional integrated circuits

Part 3: Model and measurement conditions of through-silicon via

National foreword

This British Standard is the UK implementation of IEC 63011-3:2018.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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colour
inside

Integrated circuits – Three dimensional integrated circuits –
Part 3: Model and measurement conditions of through-silicon via

Circuits intégrés – Circuits intégrés tridimensionnels –
Partie 3: Modèle et conditions de mesure des trous de liaison à travers le silicium

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